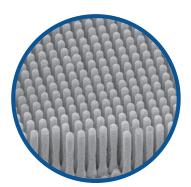
Nanolmprint Lithography (NIL) Foundry

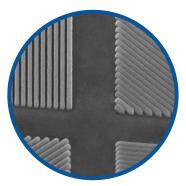
NIL Series Datasheet



Beam Shaping/Collimation (Metalens)

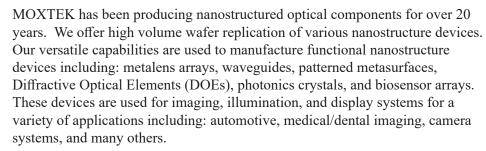


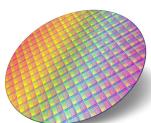
Beam Generators (Dot Arrays, Structured Light)



Patterned NanoStructure Arrays (Beamsplitters, Waveguides)

Contact Moxtek to discuss your unique designs and fabrication needs.





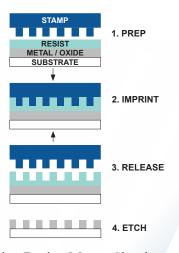
Ø200mm Wafers



Moxtek collaborates with customers to design, verify and create solutions for high volume manufacturing. We provide options for prompt design iterations and print optimization. Moxtek uses Statistical Process Control (SPC) monitoring of post-print Critical Dimension (CD) repeatability.

Our capabilities include:

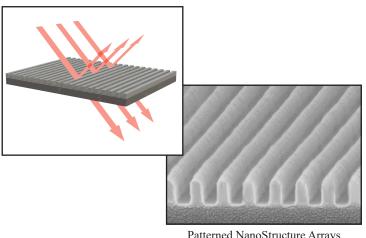
- High Volume Manufacturing
- NanoImprint Lithography (NIL)
- Metastructure Simulation and Design
- Design Master Shuttle
- Master creation, Stamp making
- Deposition (PECVD, Sputter, ALD)
- Etching (metals, oxides low to high refractive index)
- AFM and SEM
- Optical metrology and inspection
- Automated Visual Inspection



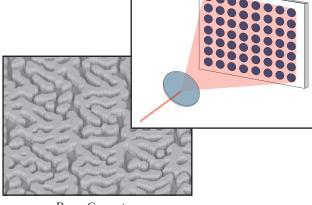
Moxtek offers prototyping samples on our recurring Design Master Shuttle. This NIL Design Master Shuttle includes space for multiple (different) design structures, which allows engineers to test several designs on a single shuttle iteration thereby reducing development time/cost. We can add your unique design on our next Design Master Shuttle for prototyping your latest lens or nanostructure optical device. These design shuttles are processed multiple times a year.

Moxtek has over 25,000 ft² of clean room space dedicated to high volume manufacturing. We offer state of the art manufacturing on Ø200mm wafers, with annual wafer volume capability of hundreds of thousands of wafers per year.

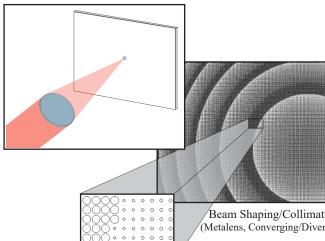




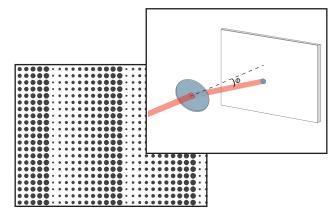
Patterned NanoStructure Arrays (Beamsplitter, Waveguides)



Beam Generators (Dot Array, Structured Light)

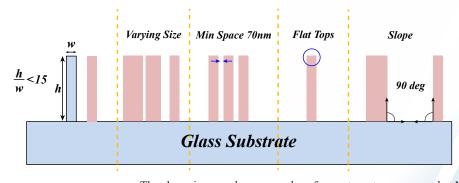


Beam Shaping/Collimation (Metalens, Converging/Diverging)



Beam Diffraction/Steering (Flat Blazed Gratings)

Parameters	Design Constraints
Minimum CD	50nm
Minimum Space Gap	70nm
Thickness	≤ 1,000nm
Meta Materials (preferred)	Nb ₂ O ₅ , Al
Meta Materials (other)	Si, SiO ₂ , Si ₃ N ₄
Substrate Diameter	Ø200mm diameter
Substrate Thicknesses	0.7mm to 1.6mm thick
Substrate Types	Display glass, Fused Silica, Silicon, Sapphire





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The above images show examples of nanostrucutres processed at Moxtek and applications. Contact Moxtek to learn more about design possibilities and options to test your design on the Design Master Shuttle.